

Title (en)
DETECTING DEFECTS ON A WAFER

Title (de)
ERKENNUNG VON DEFECTEN AUF EINEM WAFER

Title (fr)
DETECTION DES DÉFAUTS SUR UNE TRANCHE

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Application
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Abstract (en)
[origin: WO2010093733A2] Methods and systems for detecting defects on a wafer are provided.

IPC 8 full level
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